

Dual zener diodes

BZ5239CAN3/BZ5239CCN3

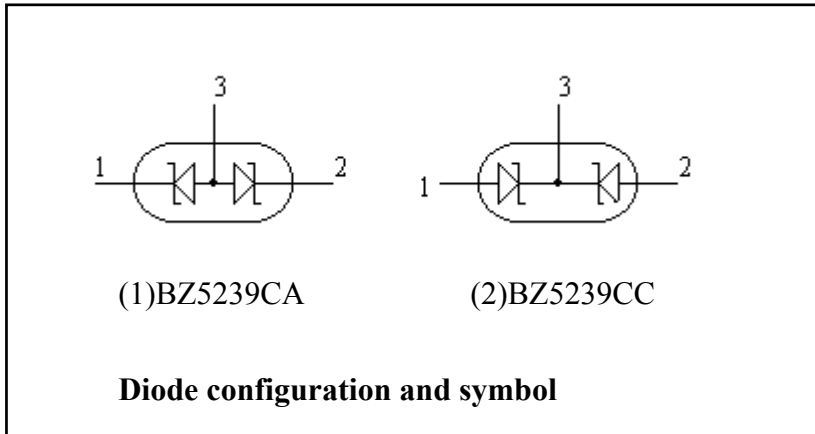
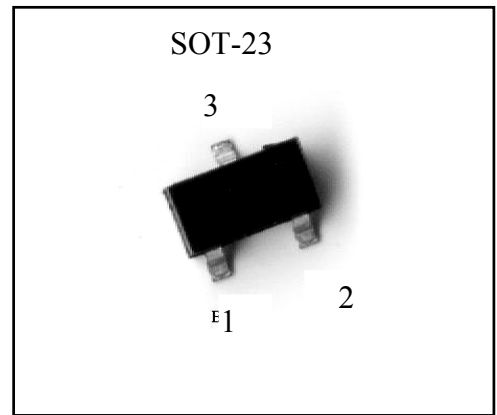
Description

Two ZD5239 diodes are encapsulated in a SOT-23 small plastic SMD package. Two different pinnings are available.

Pinning

| Pin | Description | |
|-----|-------------|----------|
| | BZ5239CA | BZ5239CC |
| 1 | K1 | A1 |
| 2 | K2 | A2 |
| 3 | A1,A2 | K1,K2 |

Outline



Marking:

| Type | Marking Code |
|------------|--------------|
| BZ5239CAN3 | 29A |
| BZ5239CCN3 | 29C |

Thermal Characteristics

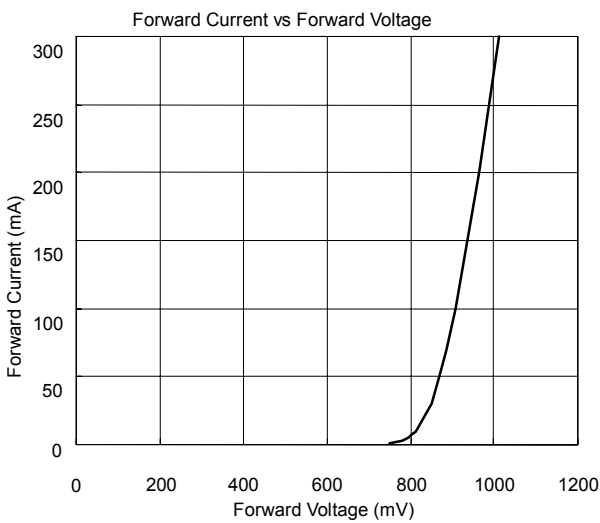
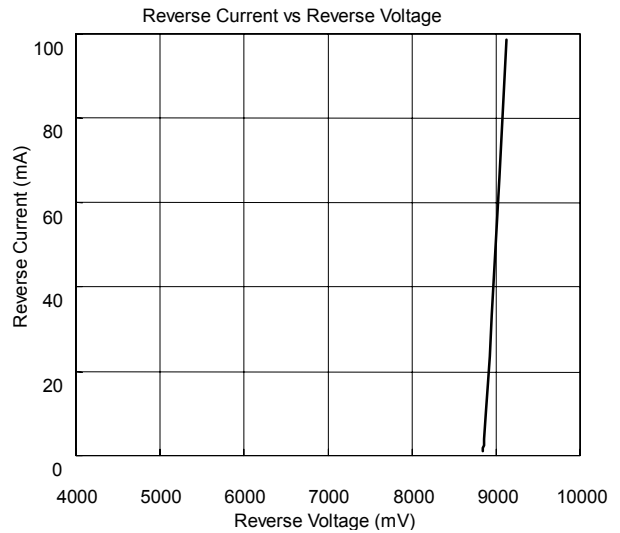
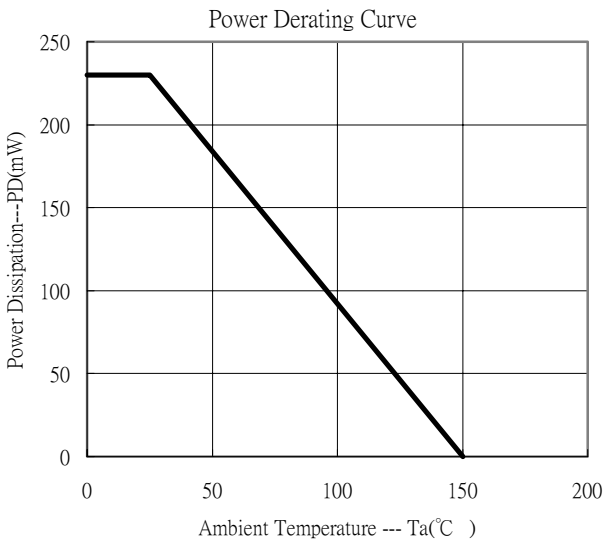
- Maximum Temperatures
 - Storage Temperature Tstg -55~+150 °C
 - Junction Temperature Tj +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Ta=25°C) Ptot 230 mW
- Thermal Resistance, Junction to Ambient θJA.....543 °C/W



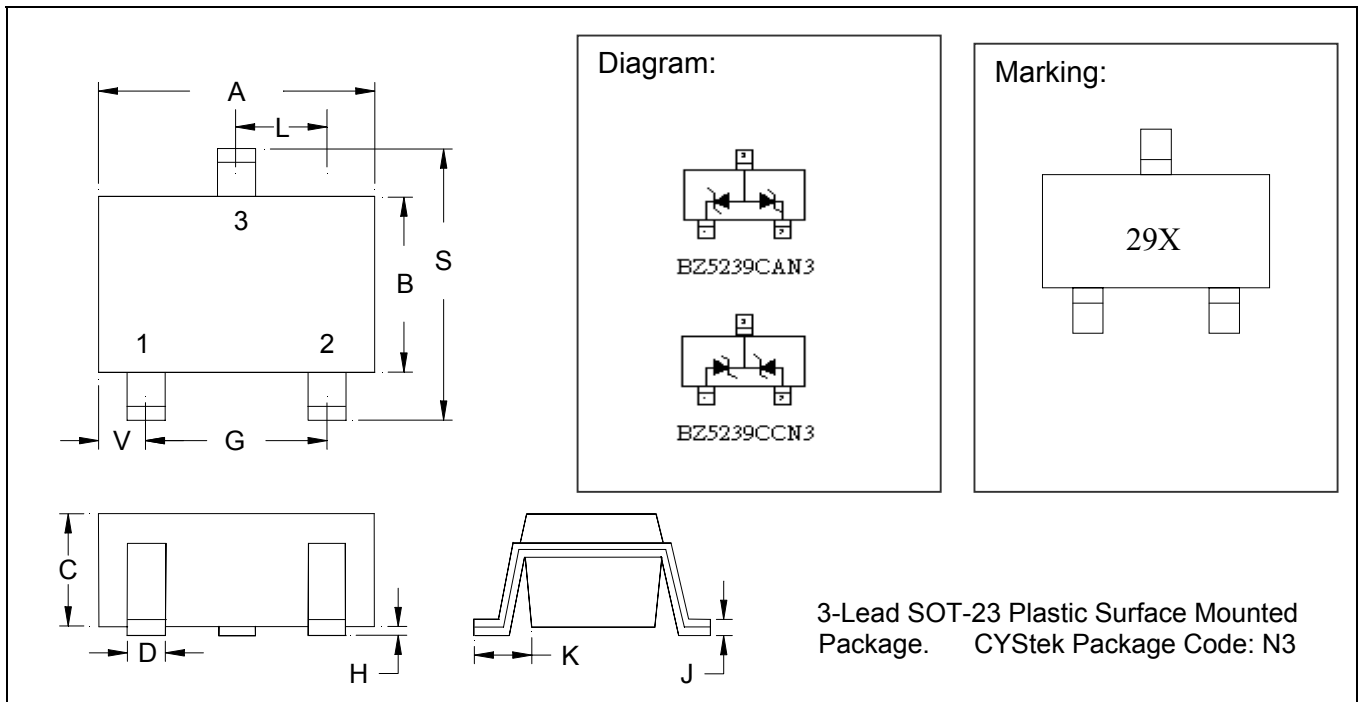
Electrical Characteristic ($V_F=0.9V$ Max @ $I_F=10mA$.)

| Test Current $I_{ZT}(mA)$ | Zener Voltage $V_Z(V)$ | Z_{ZK} $I_Z=0.25mA$ (Ω , max) | Z_{ZT} $I_Z=I_{ZT}$ (Ω , max) | Maximum Reverse Current | |
|------------------------------|---------------------------|---|---|-------------------------|----------|
| | | | | $I_R(\mu A)$ | $V_R(V)$ |
| 20 | $9.1 \pm 5\%$ | 600 | 10 | 3.0 | 7.0 |

Characteristic Curves



SOT-23 Dimension



- BZ5239CAN3: Common Anode. (Marking Code : 29A)
- BZ5239CCN3: Common Cathode. (Marking Code : 29C)

*: Typical

| DIM | Inches | | Millimeters | | DIM | Inches | | Millimeters | |
|-----|--------|--------|-------------|------|-----|--------|--------|-------------|-------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| A | 0.1102 | 0.1204 | 2.80 | 3.04 | J | 0.0034 | 0.0070 | 0.85 | 0.177 |
| B | 0.0472 | 0.0630 | 1.20 | 1.60 | K | 0.0128 | 0.0266 | 0.32 | 0.67 |
| C | 0.0335 | 0.0512 | 0.89 | 1.30 | L | 0.0335 | 0.0453 | 0.85 | 1.15 |
| D | 0.0118 | 0.0197 | 0.30 | 0.50 | S | 0.0830 | 0.1083 | 2.10 | 2.75 |
| G | 0.0669 | 0.0910 | 1.70 | 2.30 | V | 0.0098 | 0.0256 | 0.25 | 0.65 |
| H | 0.0005 | 0.0040 | 0.013 | 0.10 | | | | | |

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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